

```
graph TD; 101[Gate Metal Sputtering] --> 102[Gate Pattern]; 102 --> 103["n+a-Si/a-Si/SiNx Depositing"]; 103 --> 104[a-Si Pattern]; 104 --> 105[S/D Metal Sputtering]; 105 --> 106[S/D Pattern]; 106 --> 107[n+a-Si Etch]; 107 --> 108[SiNx Depositing]; 108 --> 109[Passivation Etch]; 109 --> 110[ITO Sputtering]; 110 --> 111[ITO Pattern];
```

101 Gate Metal Sputtering

102 Gate Pattern

103 n+a-Si/a-Si/SiNx Depositing

104 a-Si Pattern

105 S/D Metal Sputtering

106 S/D Pattern

107 n+a-Si Etch

108 SiNx Depositing

109 Passivation Etch

110 ITO Sputtering

111 ITO Pattern

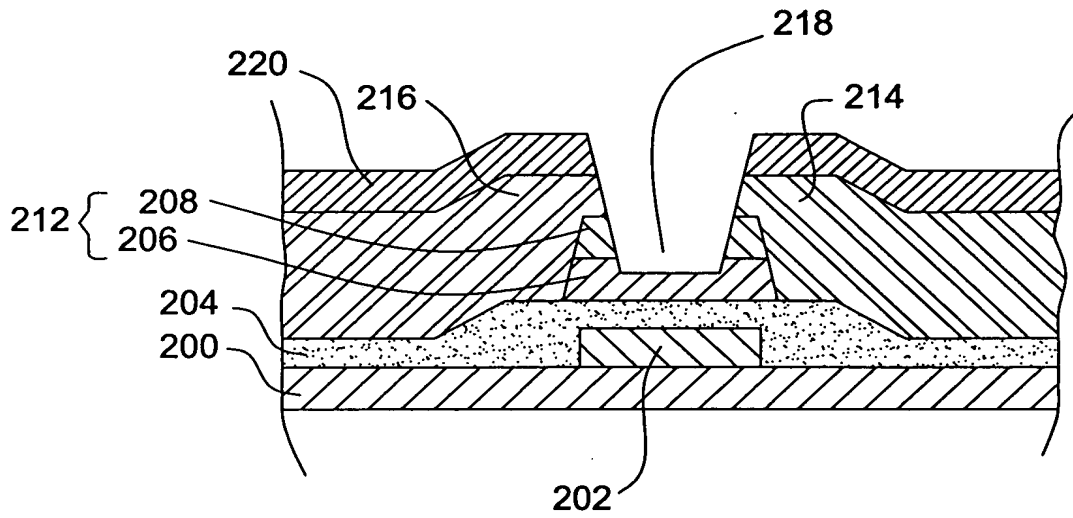


FIG. 2d (PRIOR ART)

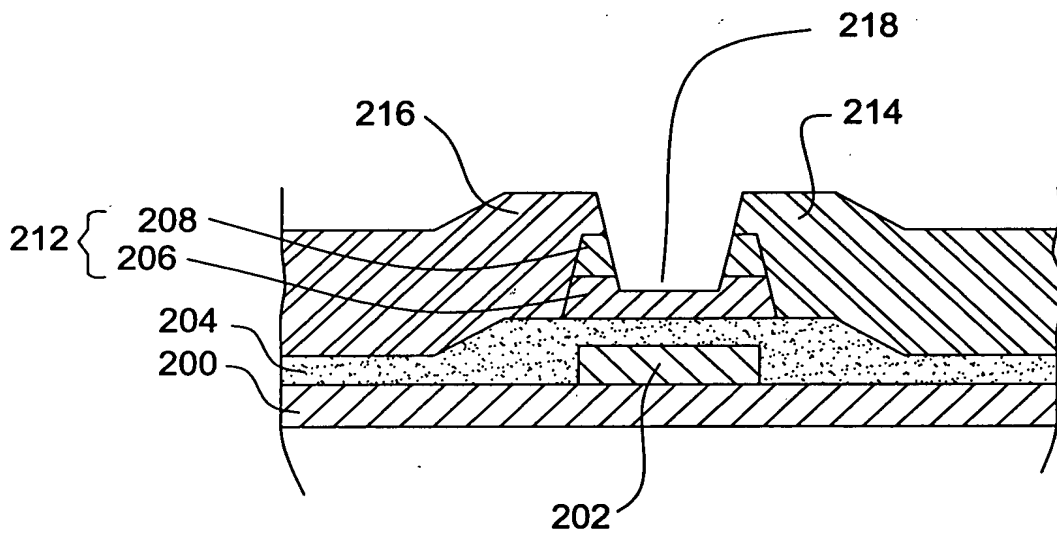


FIG. 2e (PRIOR ART)

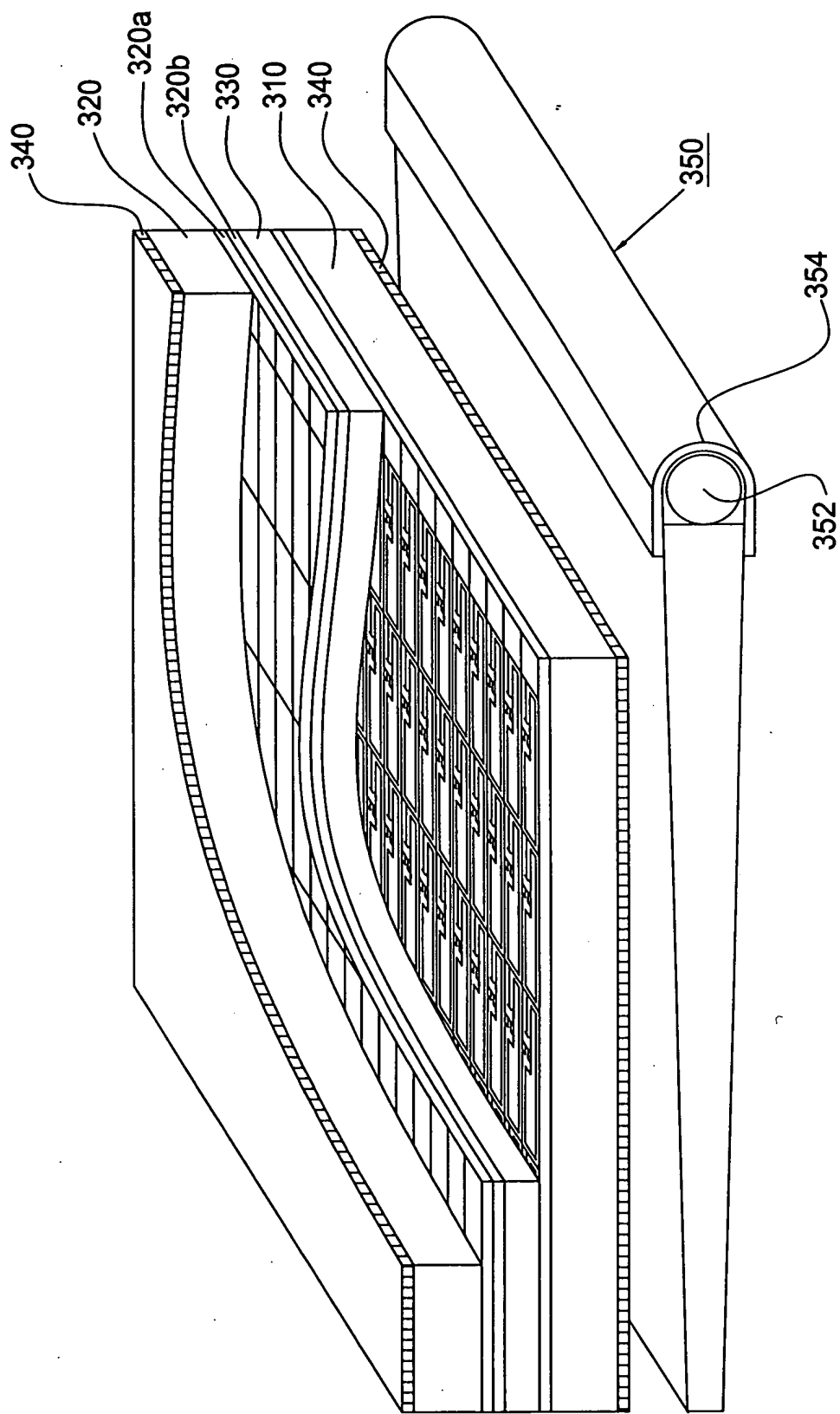


FIG. 3

FIG. 4

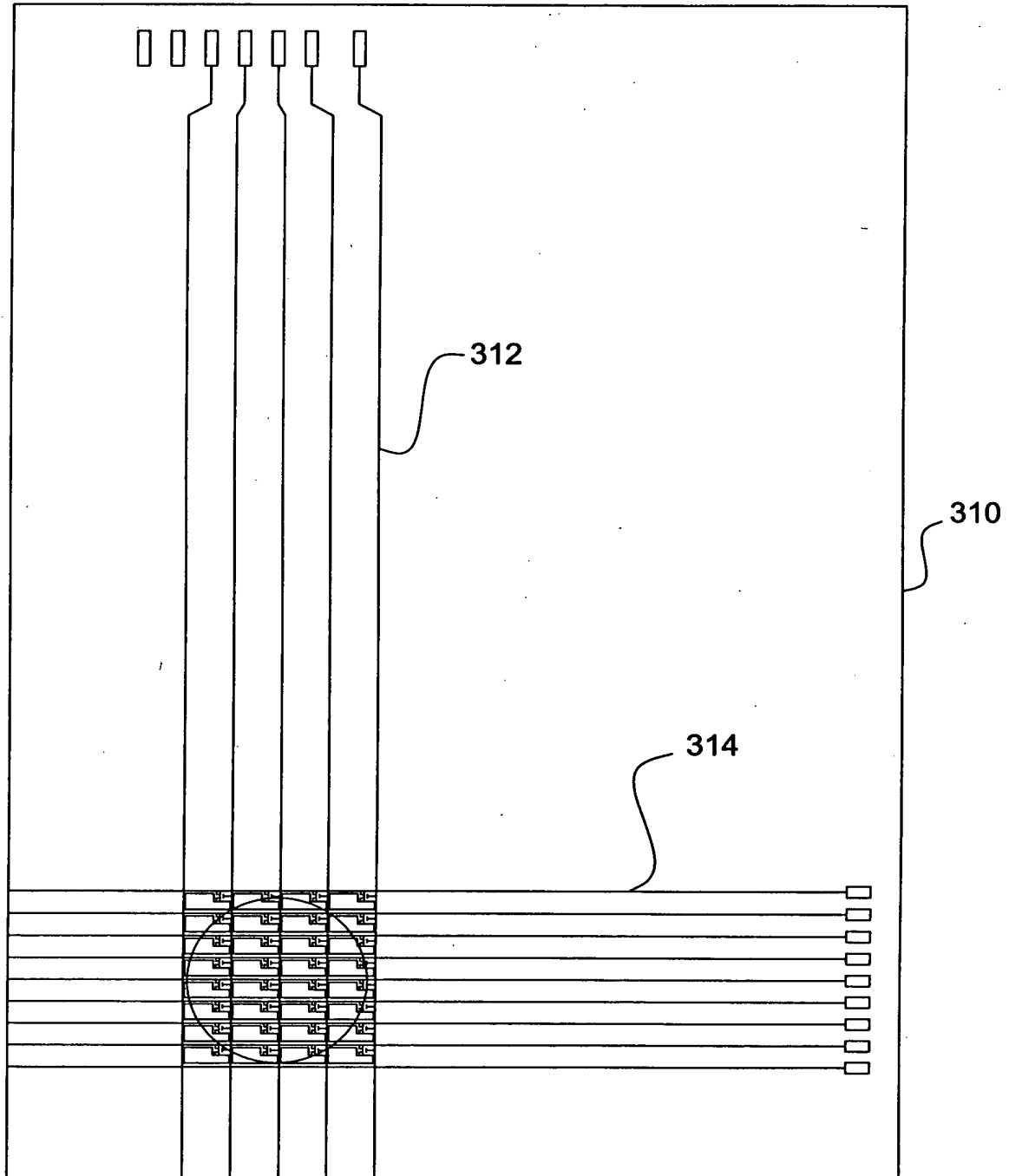
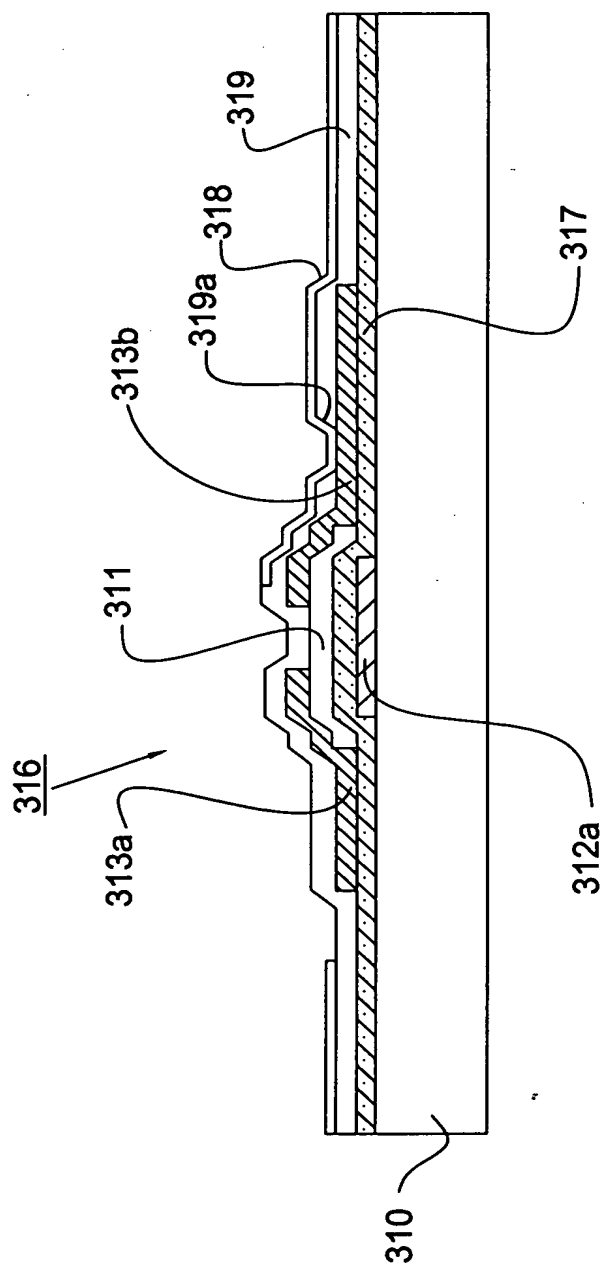


FIG. 4



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G.
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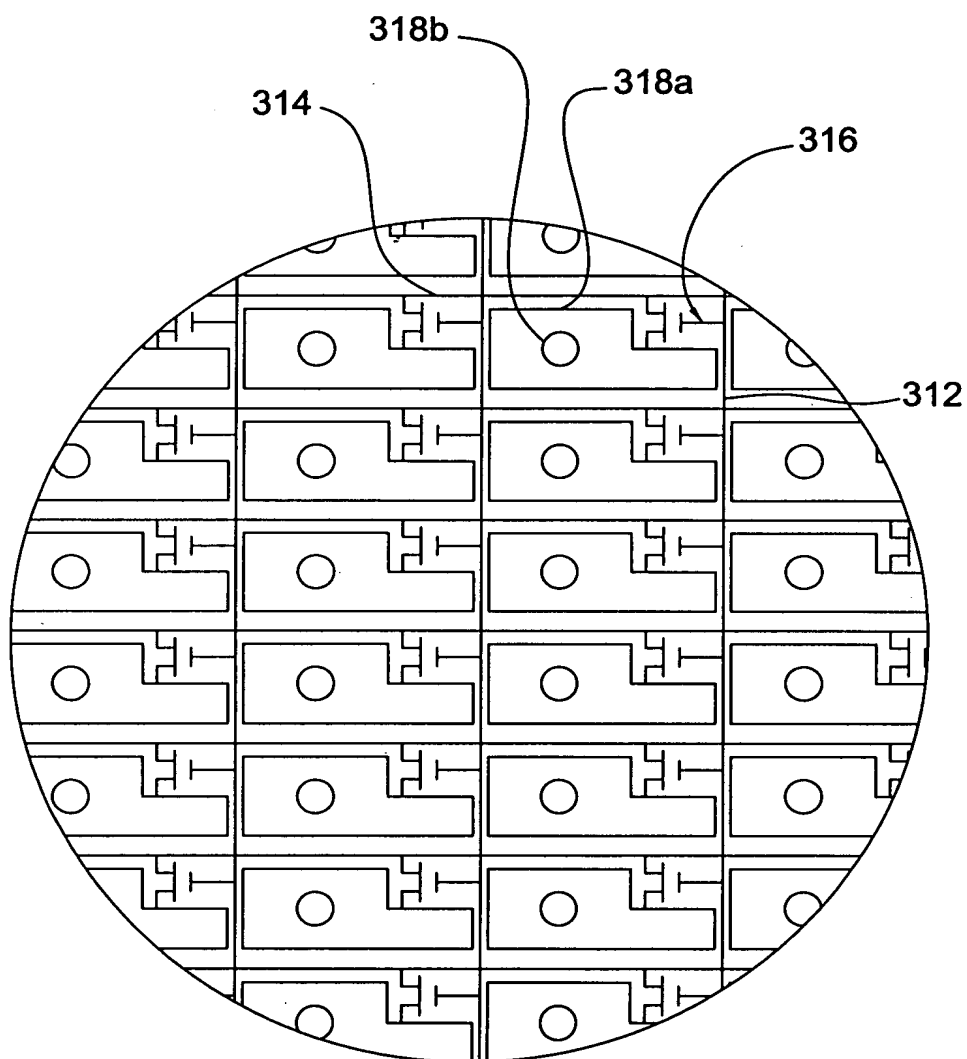


FIG. 6